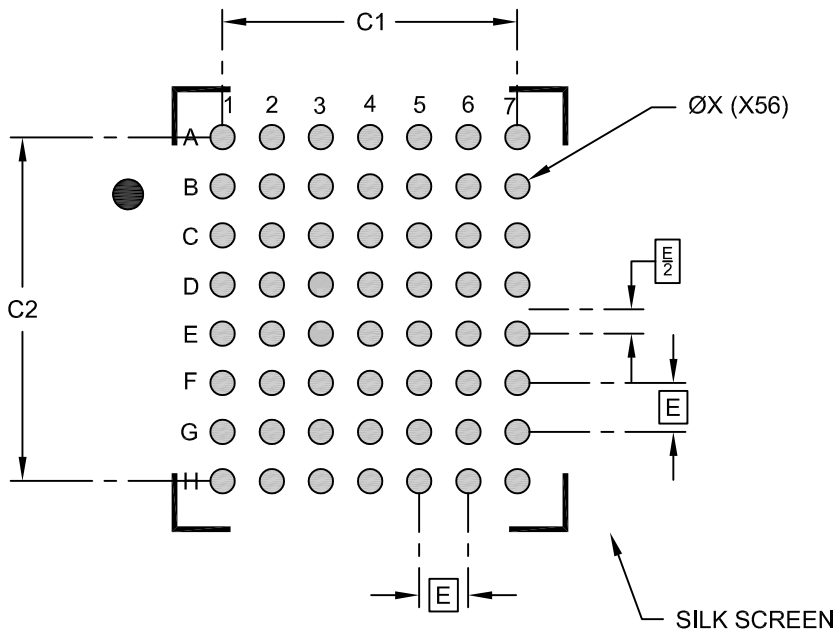


# 56-ball Wafer Level Chip Scale Package (FZB) - 3.170x3.444x0.483 mm Body [WLCSP] Atmel Legacy GPC GBL

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



## RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	0.40 BSC			
Center Ball Diameter (X56)	X				0.200
Contact Pad Spacing	C1		2.40		
Contact Pad Spacing	C2		2.80		

### Notes:

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process